

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

- 5 1. (Previously Presented) A light-emitting device with compound substrate comprising:
 - a compound substrate comprising a high thermal conductive layer and a substrate disposed around the high thermal conductive layer;
 - a transparent adhesive layer formed on the compound substrate; and
- 10 a light-emitting stack layer formed on the transparent adhesive layer.
2. (Cancelled)
3. (Previously Presented) The light-emitting device of claim 1 wherein the transparent adhesive layer is a conductive transparent adhesive layer.
- 15 4. (Previously Presented) The light-emitting device of claim 1 wherein the transparent adhesive layer is an insulating transparent adhesive layer.
- 20 5-7. (Cancelled)
8. (Previously Presented) The light-emitting device of claim 1 further comprising a first reaction layer between the compound substrate and the transparent adhesive layer.
- 25 9. (Previously Presented) The light-emitting device of claim 1 further comprising a second reaction layer between the transparent adhesive layer and the light-emitting stack layer.

10. (Original) The light-emitting device of claim 8 further comprising a metal reflecting layer between the compound substrate and the first reaction layer.

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11. (Original) The light-emitting device of claim 9 further comprising a metal reflecting layer between the second reaction layer and the light-emitting stack layer.

10 12. (Original) The light-emitting device of claim 11 further comprising a transparent conductive layer between the metal reflecting layer and the light-emitting stack layer.

13-14. (Cancelled)

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15. (Original) The light-emitting device of claim 1 further comprising a connection layer between the high thermal conductive layer and the substrate.

20 16. (Previously Presented) The light-emitting device of claim 1 wherein the high thermal conductive layer comprises at least one material selected from a material group consisting of Cu, Al, Au, Ag, W, and alloys of these metals.

25 17. (Previously Presented) The light-emitting device of claim 15 wherein the connection layer comprises at least one material selected from a material group consisting of indium tin oxide, GeAu, BeAu, Au, SiNx, SiO₂, Cu, Ti, and Pd.

18. (Cancelled)

19. (Previously Presented) The light-emitting device of claim 1 wherein the
5 transparent adhesive layer comprises at least one material selected from a material group consisting of polyimide (PI), benzocyclobutane (BCB), and perfluorocyclobutene (PFCB).

10 20. (Previously Presented) The light-emitting device of claim 3 wherein the conductive transparent adhesive layer comprises at least one material selected from a material group consisting of intrinsically conducting polymer and polymer doped with a conductive material.

15 21. (Previously Presented) The light-emitting device of claim 20 wherein the conductive material comprises at least one material selected from a material group consisting of indium tin oxide, cadmium tin oxide, antimony tin oxide, zinc oxide, zinc tin oxide, Au, and Ni/Au.

22-24. (Cancelled)

20 25. (Previously Presented) The light-emitting device of claim 8 wherein the first reaction layer comprises at least one material selected from a material group consisting of SiNx, Ti, and Cr.

25 26. (Previously Presented) The light-emitting device of claim 9 wherein the second reaction layer comprises at least one material selected from a material group consisting of SiNx, Ti, and Cr.

27. (Previously Presented) A light-emitting device with compound substrate comprising:

a compound substrate comprising a high thermal conductive layer and
a substrate disposed around the high thermal conductive layer;
5 an opaque adhesive layer formed on the compound substrate; and
a light-emitting stack layer formed on the opaque adhesive layer.

28. (Previously Presented) The light-emitting device of claim 27 wherein
the opaque adhesive layer is a conductive opaque adhesive layer.

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29. (Previously Presented) The light-emitting device of claim 27 wherein
the opaque adhesive layer is an insulating opaque adhesive layer.

30. (Previously Presented) The light-emitting device of claim 27 further
15 comprising a first reaction layer between the compound substrate and the
opaque adhesive layer.

31. (Previously Presented) The light-emitting device of claim 30 further
comprising a second reaction layer between the opaque adhesive layer
20 and the light-emitting stack layer.

32. (Previously Presented) The light-emitting device of claim 31 further
comprising a metal reflecting layer between the second reaction layer
and the light-emitting stack layer.

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33. (Previously Presented) The light-emitting device of claim 32 further
comprising a transparent conductive layer between the metal reflecting
layer and the light-emitting stack layer.

34. (Previously Presented) The light-emitting device of claim 27 further comprising a connection layer between the high thermal conductive layer and the substrate.

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35. (Previously Presented) The light-emitting device of claim 27 wherein the high thermal conductive layer comprises at least one material selected from a material group consisting of Cu, Al, Au, Ag, W, and alloys of these metals.

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36. (Previously Presented) The light-emitting device of claim 34 wherein the connection layer comprises at least one material selected from a material group consisting of indium tin oxide, GeAu, BeAu, Au, SiNx, SiO₂, Cu, Ti, and Pd.

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37. (Previously Presented) The light-emitting device of claim 30 wherein the first reaction layer comprises at least one material selected from a material group consisting of SiNx, Ti, and Cr.

20 38. (Previously Presented) The light-emitting device of claim 31 wherein the second reaction layer comprises at least one material selected from a material group consisting of SiNx, Ti, and Cr.

25 39. (Currently Amended) A light-emitting device with compound substrate comprising:

a compound substrate comprising a high thermal conductive layer and a substrate disposed around the high thermal conductive layer; a metal adhesive layer formed on the compound substrate; and

a metal reflecting layer formed on the metal adhesive layer; and
a light-emitting stack layer formed on the metal reflecting layer[[:]];
~~wherein the metal layer is formed to enhance adhesion between the~~
~~compound substrate and the light-emitting stack layer.~~

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40. (Cancelled)

41. (Currently Amended) The light-emitting device of claim [[40]]39
further comprising a transparent conductive layer between the metal
10 reflecting layer and the light-emitting stack layer.

42. (Previously Presented) The light-emitting device of claim 39 further
comprising a connection layer between the high thermal conductive layer
and the substrate.

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43. (Previously Presented) The light-emitting device of claim 39 wherein
the high thermal conductive layer comprises at least one material
selected from a material group consisting of Cu, Al, Au, Ag, W, and
alloys of these metals.

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44. (Previously Presented) The light-emitting device of claim 42 wherein
the connection layer comprises at least one material selected from a
material group consisting of indium tin oxide, GeAu, BeAu, Au, SiNx,
SiO₂, Cu, Ti, and Pd.

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45. (Currently Amended) The light-emitting device of claim 39 wherein the
metal adhesive layer comprises at least one material selected from a
material group consisting of In, Sn, Al, Au, Pt, Zn, Ge, Ag, Ti, Pb, Pd,

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Cu, and alloys of these metals.

46. (Currently Amended) The light-emitting device of claim 39 wherein the metal adhesive layer is a metal reflecting adhesive layer.

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